

Title (en)

METHOD FOR PRODUCING A SECURITY ELEMENT WITH NEGATIVE INSCRIPTION

Title (de)

VERFAHREN ZUM HERSTELLEN EINES SICHERHEITSELEMENTS MIT NEGATIVSCHRIFT

Title (fr)

PROCÉDÉ SERVANT À FABRIQUER UN ÉLÉMENT DE SÉCURITÉ POURVU D'UNE INSCRIPTION NÉGATIVE

Publication

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Application

**EP 14715838 A 20140403**

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Abstract (en)

[origin: WO2014161667A1] The invention relates to a method for producing a security element (1) with negative inscription (3), comprising the following steps: a) producing a first security element sub-element (10) by providing a first carrier substrate (11), applying a first functional layer (12) to the first carrier substrate (11), applying a resistance layer (30) to the first functional layer (12) in the form of a pre-determined pattern (7) with resistance areas (33) and recesses (34) between the resistance areas; b) producing a second security element sub-element (20) by providing a second carrier substrate (21), applying a second functional layer (22) to the first second substrate (21); c) assembling the first (10) and the second (20) security element sub-element to form a composite (5) such that the resistance layer (30) and the second functional layer (22) face each other, and adhering the first (10) and the second (20) security element sub-elements together; d) separating the second carrier substrate (21) from the adhered composite (5), said second functional layer (22) remaining adhered to the resistance layer (33) due to the formation of the second functional layer (23), whilst the remaining areas of the second functional layer (22) are separated together with the second carrier substrate (21), second recesses (24) being formed in the second functional layer (22). and e) removing the area of the first functional layer (12) not protected by the resistance area (33) by means of etching in order to form first functional areas (13) and first recesses (14), which form together with the recesses (34) in the resistance layer (30) and the second recesses (24) in the second functional layer (22) made of a material which is resistance to etching, the negative inscription (3).

IPC 8 full level

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